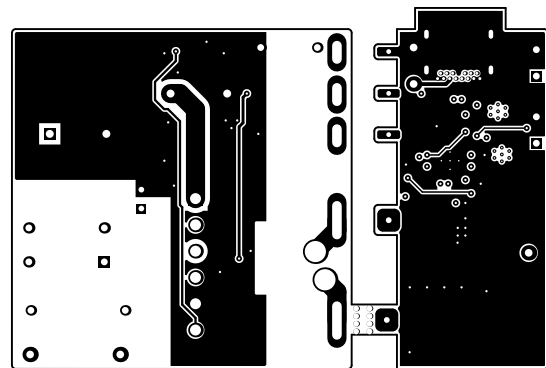
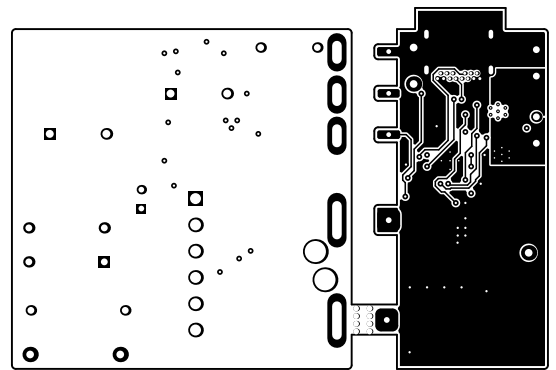


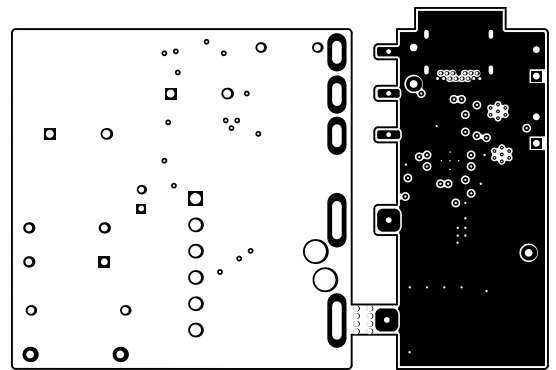
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 1/24/2017 7:31:44 PM	TEXAS INSTRUMENTS	



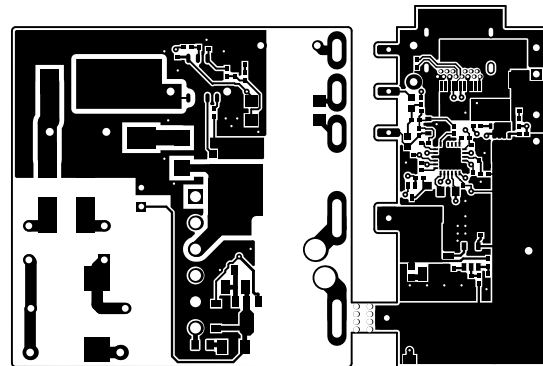
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 1/24/2017 7:31:45 PM	TEXAS INSTRUMENTS	



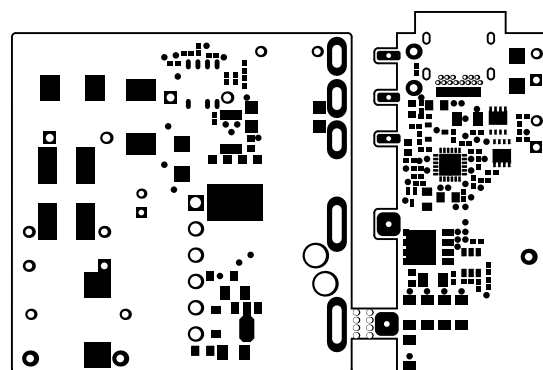
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 1/24/2017 7:31:46 PM	TEXAS INSTRUMENTS	



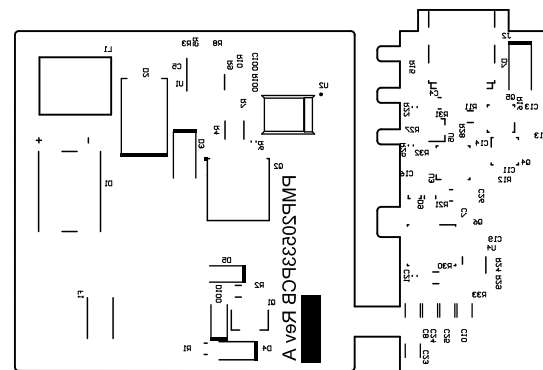
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 1/24/2017 7:31:47 PM	TEXAS INSTRUMENTS	



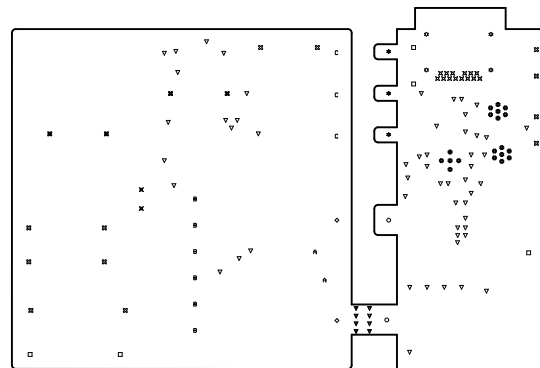
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 1/24/2017 7:31:48 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 1/24/2017 7:31:49 PM	TEXAS INSTRUMENTS	



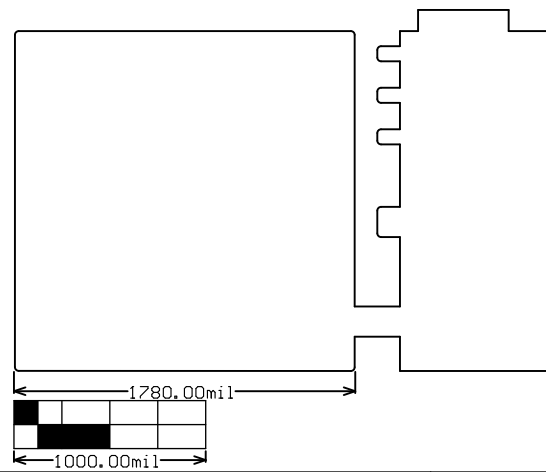
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 1/24/2017 7:31:50 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	8	30,00mil (0.762mm)	NPTH	Round	Top Layer - Bottom Layer	
⊕	19	7,87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
▽	54	12,00mil (0,305mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	14	15,75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	3	25,00mil (0.635mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	29,53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	30,00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	12	35,43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	5	40,00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	41,34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
B	6	57,09mil (1.450mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	110,24mil (2.800mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	23,62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
C	3	50,00mil (1.270mm)	PTH	Slot	Top Layer - Bottom Layer	
◇	2	50,00mil (1.270mm)	PTH	Slot	Top Layer - Bottom Layer	
	140 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size + Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 1/24/2017 7:31:51 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20533	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 1/24/2017 7:31:52 PM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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